

Amendments to the Abstract:

Please replace the original abstract with the following abstract.

ABSTRACT

A method of fabricating ~~method of~~ a semiconductor integrated circuit device uses a mold which is provided with a plurality of air vents and movable pins which are formed such that the movable pins include grooves in the distal ends thereof and which project into the air vents. By clamping the mold in a state such that the distal ends of the movable pins are pushed ~~to~~ against a multi-cavity board at the time of clamping the mold, resin can be filled while leaking air inside the cavity through the grooves formed in the distal ends of the movable pins by setting the depths of the respective air vents to a fixed value irrespective of the irregularities ~~of thicknesses in~~ thickness of the multi-cavity boards. Accordingly, it is possible to prevent ~~the~~ occurrence ~~of~~ of insufficient filling of resin in the cavity, the occurrence ~~of~~ of leaking of resin or defective welding, whereby a ~~the~~ yield rate of products can be enhanced.